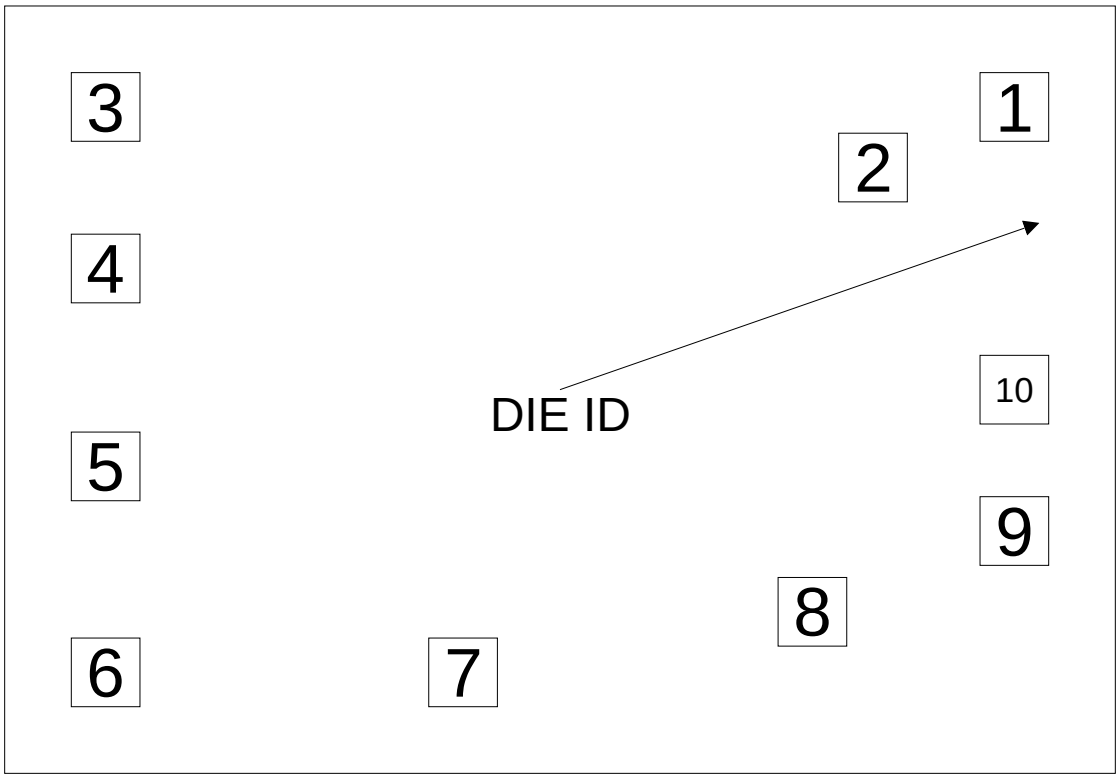
LM161 MD8
High Speed Differential Comparator

6-Jan-2011

DIE LAYOUT (E-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM161E	Bond Pad Opening Size (min)	86.36µm x 86.36µm
Die Step	E	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	PECVDOX NITRIDE
Wafer Diameter	152.4mm	Back Side Metal	Bare Back
Die Size (Drawn)	1397.0µm x 965.2µm 55.0mils x 38.0mils	Back Side Connection	Floating or -VCC
Thickness	304.8µm Nominal		
Min Pitch	177.80µm		
Note: All values are rounded to the nearest micron.			
Special Assembly Requirements:			

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Die Bond Pad Coordinate Locations(E-Step)
(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X		Y
INPUT 1	1	571.50	355.60	86.36	x	86.36
INPUT 2	2	393.70	279.40	86.36	x	86.36
V-	3	-571.50	355.60	86.36	x	86.36
STROBE 2	4	-571.50	152.40	86.36	x	86.36
OUTPUT 2	5	-571.50	-96.52	86.36	x	86.36
GND	6	-571.50	-355.60	86.36	x	86.36
OUTPUT 1	7	-121.92	-355.60	86.36	x	86.36
STROBE 1	8	317.50	-279.40	86.36	x	86.36
Vcc	9	571.50	-177.80	86.36	x	86.36
V+	10	571.50	0.00	86.36	x	86.36

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Notes

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